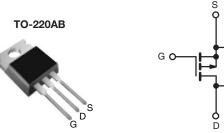


Vishay Siliconix



Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	- 200				
R _{DS(on)} (Ω)	V _{GS} = - 10 V 1.5				
Q _g (Max.) (nC)	22				
Q _{gs} (nC)	12				
Q _{gd} (nC)	10				
Configuration	Single				



P-Channel MOSFET

FEATURES

- Dynamic dV/dt Rating
- P-Channel
- Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9620PbF
Lead (FD)-fiee	SiHF9620-E3
SnPb	IRF9620
SIFD	SiHF9620

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	- 200	v	
Gate-Source Voltage			V _{GS}	± 20	v	
Continuous Drain Current	V at 10.V	T _C = 25 °C T _C = 100 °C	- I _D	- 3.5		
	V _{GS} at - 10 V	T _C = 100 °C		- 2.0	А	
Pulsed Drain Current ^a			I _{DM}	- 14		
Linear Derating Factor				0.32	W/°C	
Maximum Power Dissipation	$T_{\rm C} = 2$	25 °C	PD	40	W	
Peak Diode Recovery dV/dt ^b			dV/dt	- 5.0	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150		
Soldering Recommendations (Peak Temperature)	for ⁻	10 s		300 ^c	- °C	
Mounting Torque	6-32 or M3 screw			10	lbf ∙ in	
Mounting Torque				1.1	N⋅m	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. $I_{SD} \leq$ - 3.5 A, dl/dt \leq 95 A/µs, $V_{DD} \leq V_{DS},\,T_J \leq$ 150 °C.

c. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

Document Number: 91082 S11-0512-Rev. B, 21-Mar-11



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THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP.		MAX.	MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-		62 - 3.1		-			
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50				°C/W			
Maximum Junction-to-Case (Drain)	R _{thJC}	-							
	•								
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	inless otherw	ise noted)							
PARAMETER	SYMBOL	TEST		ONS	MIN.	TYP.	MAX.	UNIT	
Static									
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	0 V, I _D = - 2	250 µA	- 200	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I	_D = - 1 mA	-	- 0.22	-	V/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V	V _{GS} , I _D = -	250 µA	- 2.0	-	- 4.0	V	
Gate-Source Leakage	I _{GSS}	l v	$t_{\rm GS} = \pm 20$	V	-	-	± 100	nA	
Zara Cata Valtaga Drain Current	1	$V_{DS} = -200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		-	-	- 100	<u> </u>		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = - 160 V	V _{DS} = - 160 V, V _{GS} = 0 V, T _J = 125 °C		-	-	- 500	μA	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V	I _D :	= - 1.5 A ^b	-	-	1.5	Ω	
Forward Transconductance		V _{DS} = -	50 V, I _D =	- 1.5 A ^b	1.0	-	-	S	
Dynamic						•			
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1.0 MHz, see fig. 5		-	350	-	pF		
Output Capacitance	C _{oss}			-	100	-			
Reverse Transfer Capacitance	C _{rss}			-	30	-			
Total Gate Charge	Qg				-	-	22		
Gate-Source Charge	Q _{gs}	V _{GS} = - 10 V	$V_{GS} = -10 \text{ V}$ $I_D = -4.0 \text{ A}, V_{DS} = -160 \text{ V},$ see fig. 11 and 18 ^b		-	-	12	nC	
Gate-Drain Charge	Q _{gd}				-	-	10		
Turn-On Delay Time	t _{d(on)}			-	15	-			
Rise Time	t _r	V _{DD} = -	100 V, I _D =	- 1.5 A,	-	25	-	1	
Turn-Off Delay Time	t _{d(off)}	$R_g = 50 \Omega, I$	$R_g = 50 \Omega$, $R_D = 67 \Omega$, see fig. 17^b		-	20	-	ns	
Fall Time	t _f			-	15	-	1		
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-			
Internal Source Inductance	L _S			-	7.5	-	- nH		
Drain-Source Body Diode Characteristic	cs						1		
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the		-	-	- 3.5	^		
Pulsed Diode Forward Current ^a	I _{SM}	p - n junction diode			-	-	- 14	A	
Body Diode Voltage	V _{SD}	$T_J = 25 \text{ °C}, I_S = -3.5 \text{ A}, V_{GS} = 0 \text{ V}^{b}$		-	-	- 7.0	V		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

t_{rr}

Q_{rr}

t_{on}

b. Pulse width \leq 300 $\mu s;$ duty cycle \leq 2 %.

Body Diode Reverse Recovery Time

Forward Turn-On Time

Body Diode Reverse Recovery Charge

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450

2.9

ns

μC

300

1.9

-

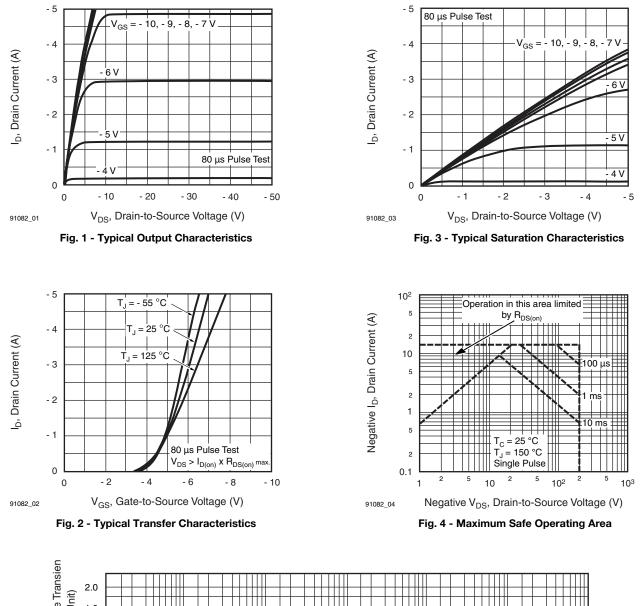
Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)

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 T_J = 25 °C, I_F = - 3.5 A, dI/dt = 100 A/ μs^b



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

 $Z_{thJC}(t)/R_{thJC},$ Normalized Effective Transien Thermal Impedence (Per Unit) 1.0 0.5 0.5 D P_{DM} 0 0.2 0.' μΠ 0.1 <t₁→ 0.05 0.05 -Notes: Single Pulse (Transient 0.01 1. Duty Factor, $D = t_1/t_2$ Thermal Impedence) 0.02 2. Per Unit Base = R_{thJC} = 3.12 °C/W Τ_{JΜ} 3. - T_C $= P_{DM} Z_{thJC}(t)$ 0.01 2 2 2 5 2 5 5 10⁻² 5 2 5 10⁻⁵ 10-4 10⁻³ 0.1 1.0 10 91082_05 t₁, Square Wave Pulse Duration (s) Fig. 5 - Maximum Effective Transient Thermal Impedance, Junction-to-Case vs. Pulse Duration

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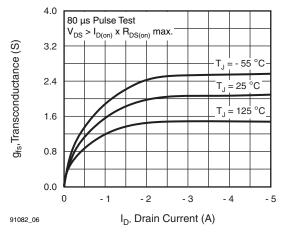


Fig. 6 - Typical Transconductance vs. Drain Current

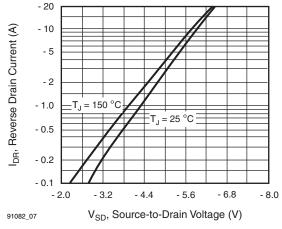
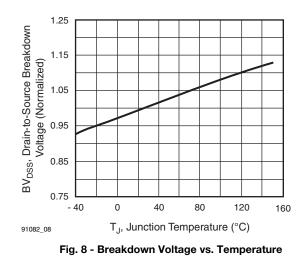


Fig. 7 - Typical Source-Drain Diode Forward Voltage



R_{DS(on)}, Drain-to-Source On Resistance 2.5 I_D = - 1.0 A 10 V GS 2.0 (Normalized) 1.5 1.0 0.5 0.0 - 40 0 40 80 120 160 T_J, Junction Temperature (°C) 91082_09

Fig. 9 - Normalized On-Resistance vs. Temperature

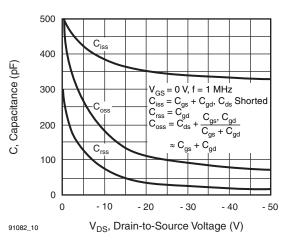
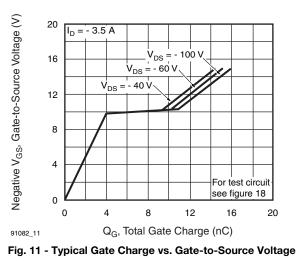


Fig. 10 - Typical Capacitance vs. Drain-to-Source Voltage



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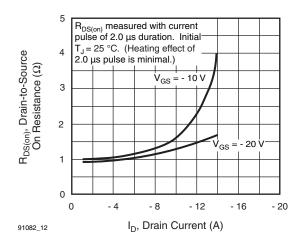


Fig. 12 - Typical On-Resistance vs. Drain Current

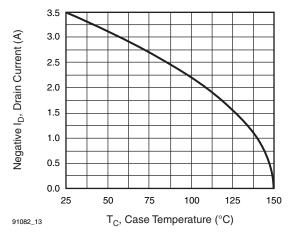
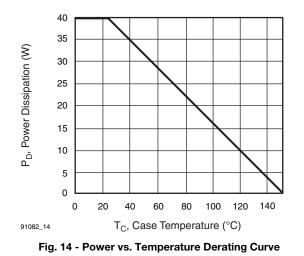


Fig. 13 - Maximum Drain Current vs. Case Temperature



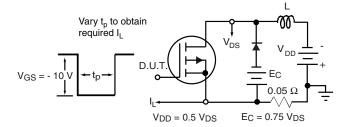


Fig. 15 - Clamped Inductive Test Circuit

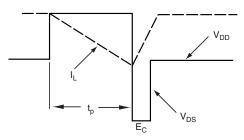


Fig. 16 - Clamped Inductive Waveforms

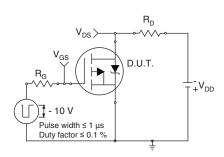


Fig. 17a - Switching Time Test Circuit

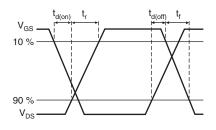


Fig. 17b - Switching Time Waveforms

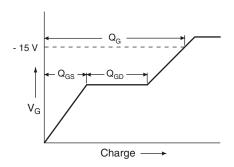
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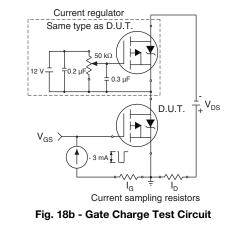
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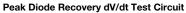
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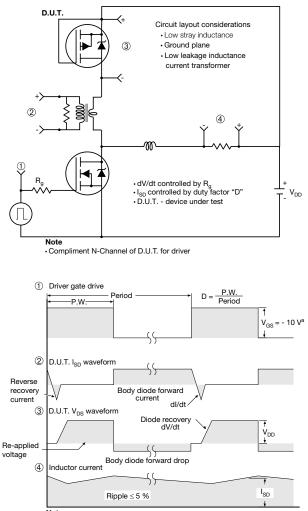












Note a. V_{GS} = - 5 V for logic level and - 3 V drive devices

Fig. 19 - For P-Channel

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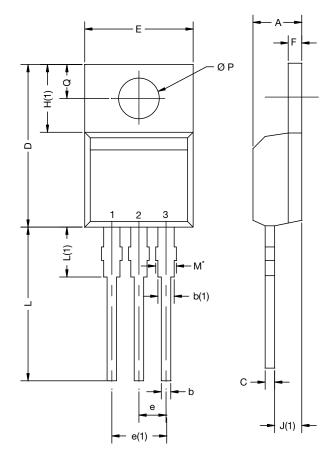
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TO-220-1



DIM.	MILLIN	IETERS	INCHES		
DIIVI.	MIN.	MAX.	MIN.	MAX.	
А	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture					
ASE		Xi'an			
		IRF 9510 744K AB			

Revison: 14-Dec-15

Document Number: 66542

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